

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B320AF	B330AF	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	20	30	v
Average Rectified Output Current	lo		3	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	٤	30	А

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R <sub>0JA</sub>	85	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R <sub>θJC</sub>	45	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-55 to +150	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

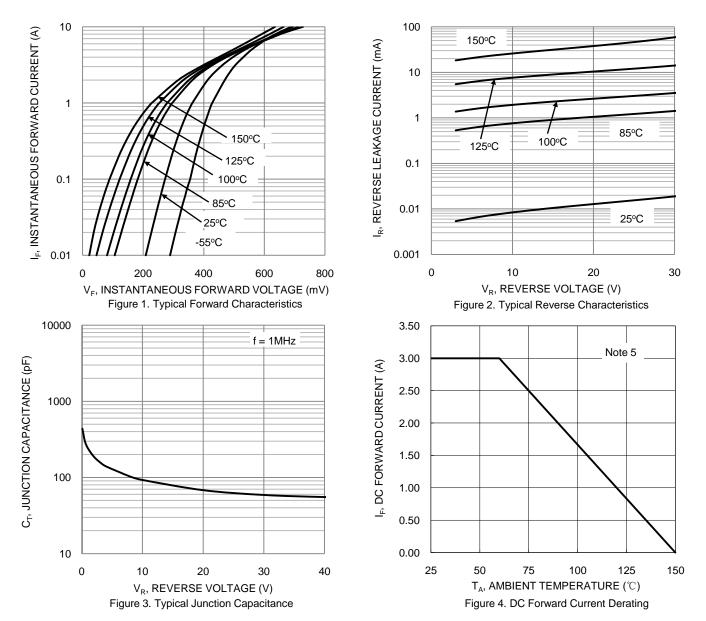
Characteristic	;	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop		V <sub>F</sub>	_	0.46 0.40	0.50 —	V	I <sub>F</sub> = 3A, T <sub>J</sub> = +25°C I <sub>F</sub> = 3A, T <sub>J</sub> = +125°C
Leakage Current (Note 6)	B320AF B330AF	I <sub>R</sub>	 	0.02 12 0.03 14.0	0.20 — 0.20 —	mA	$ \begin{split} & V_{R} = 20V, \ T_{J} = +25^{\circ}C \\ & V_{R} = 20V, \ T_{J} = +125^{\circ}C \\ & V_{R} = 30V, \ T_{J} = +25^{\circ}C \\ & V_{R} = 30V, \ T_{J} = +125^{\circ}C \end{split} $
Typical Capacitance		Ст	—	140	—	pF	V <sub>R</sub> = 4.0V, f = 1MHz

Notes:

5. Device mounted on FR-4 substrate, 0.4"\*0.5", 2oz, single-sided, PC boards with 0.2"\*0.25" copper pad.
6. Short duration pulse test used to minimize self-heating effect.



## B320AF/B330AF



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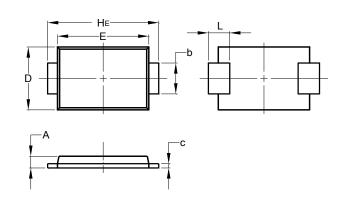
## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMAF

SMAF

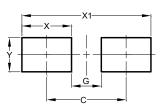
NEW PRODUCT



SMAF				
Dim	Min	Max		
Α	0.90	1.10		
b	1.25	1.65		
С	0.10	0.40		
D	2.25	2.95		
Е	3.95	4.60		
HE	4.80	5.60		
L	0.50	1.50		
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Y	1.70

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